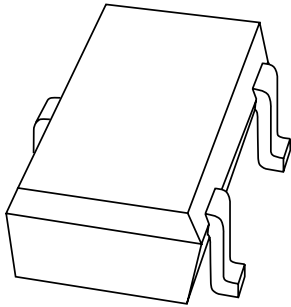


# DATA SHEET



## **1PS300** High-speed double diode

Product data sheet  
Supersedes data of 1996 Oct 04

1999 May 26

# High-speed double diode

# 1PS300

## FEATURES

- Very small plastic SMD package
- High switching speed: max. 4 ns
- Continuous reverse voltage: max. 80 V
- Repetitive peak reverse voltage: max. 85 V
- Repetitive peak forward current: max. 500 mA.

## APPLICATIONS

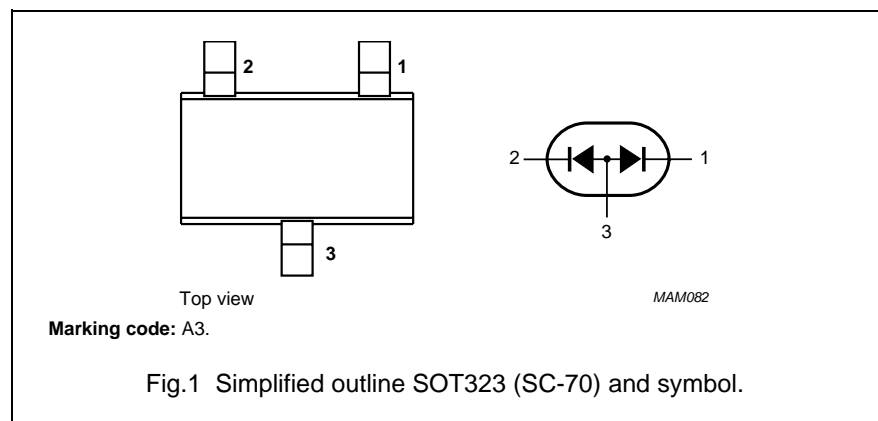
- High-speed switching in e.g. surface mounted circuits.

## DESCRIPTION

The 1PS300 consists of two high-speed switching diodes with common anodes, fabricated in planar technology, and encapsulated in the very small rectangular SOT323 (SC-70) plastic SMD package.

## PINNING

PIN	DESCRIPTION
1	cathode (k1)
2	cathode (k2)
3	common anode



## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
<b>Per diode</b>					
$V_{RRM}$	repetitive peak reverse voltage		–	85	V
$V_R$	continuous reverse voltage		–	80	V
$I_F$	continuous forward current	single diode loaded; see Fig.2; note 1	–	200	mA
		double diode loaded; see Fig.2; note 1	–	170	mA
$I_{FRM}$	repetitive peak forward current		–	500	mA
$I_{FSM}$	non-repetitive peak forward current	square wave; $T_j = 25\text{ °C}$ prior to surge			
		$t = 1\ \mu\text{s}$	–	4	A
		$t = 1\ \text{s}$	–	0.5	A
$P_{tot}$	total power dissipation	$T_{amb} = 25\text{ °C}$ ; note 1	–	300	mW
$T_{stg}$	storage temperature		–65	+150	°C
$T_j$	junction temperature		–	150	°C

## Note

1. Device mounted on an FR4 printed-circuit board.

## High-speed double diode

1PS300

**ELECTRICAL CHARACTERISTICS** $T_j = 25\text{ °C}$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
<b>Per diode</b>					
$V_F$	forward voltage	see Fig.3			
		$I_F = 1\text{ mA}$	610	–	mV
		$I_F = 10\text{ mA}$	740	–	mV
		$I_F = 50\text{ mA}$	–	1	V
		$I_F = 100\text{ mA}$	–	1.2	V
$I_R$	reverse current	see Fig.4			
		$V_R = 25\text{ V}$	–	30	nA
		$V_R = 80\text{ V}$	–	0.5	$\mu\text{A}$
		$V_R = 25\text{ V}; T_j = 150\text{ °C}$	–	30	$\mu\text{A}$
		$V_R = 80\text{ V}; T_j = 150\text{ °C}$	–	100	$\mu\text{A}$
$C_d$	diode capacitance	$f = 1\text{ MHz}; V_R = 0$ ; see Fig.5	–	2	pF
$t_{rr}$	reverse recovery time	when switched from $I_F = 10\text{ mA}$ to $I_R = 10\text{ mA}$ ; $R_L = 100\ \Omega$ ; measured at $I_R = 1\text{ mA}$ ; see Fig.6	–	4	ns
$V_{fr}$	forward recovery voltage	when switched from $I_F = 10\text{ mA}$ ; $t_r = 20\text{ ns}$ ; see Fig.7	–	1.75	V

**THERMAL CHARACTERISTICS**

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-tp}$	thermal resistance from junction to tie-point		200	K/W
$R_{th\ j-a}$	thermal resistance from junction to ambient	note 1	415	K/W

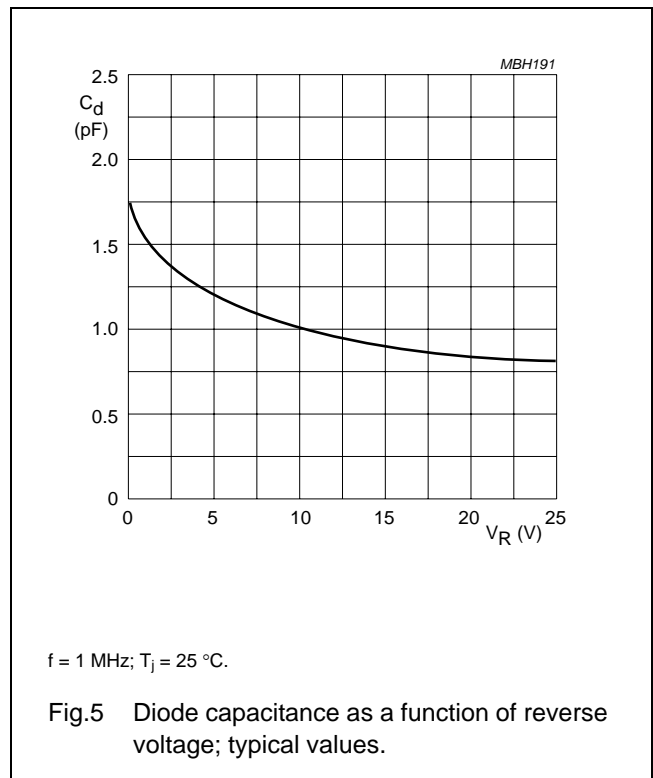
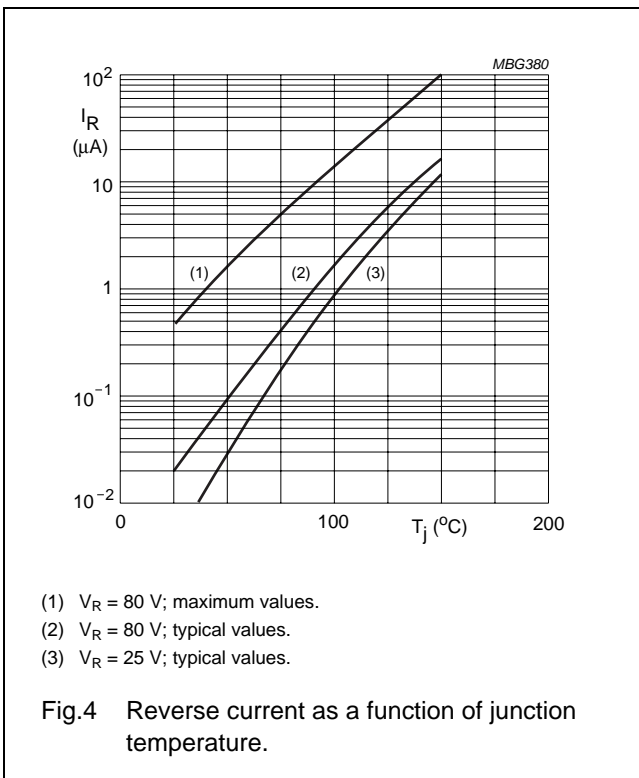
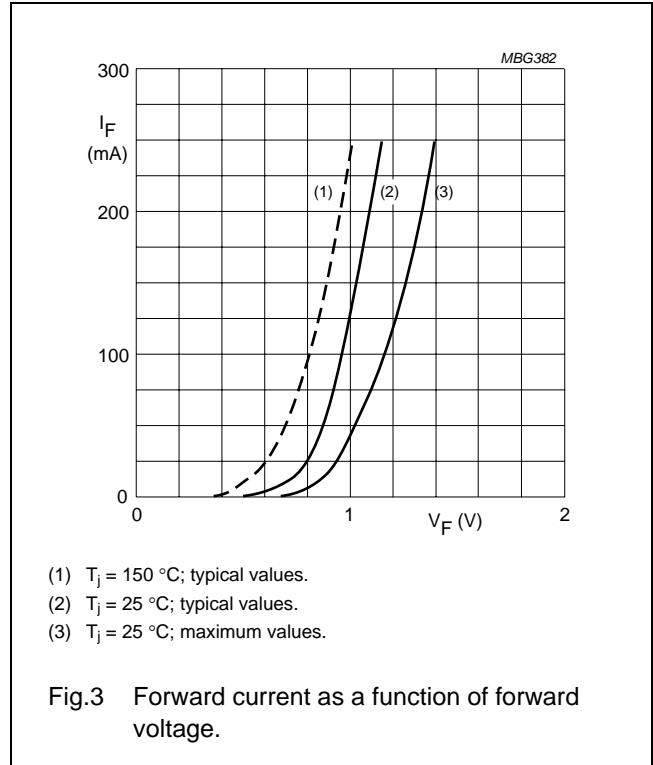
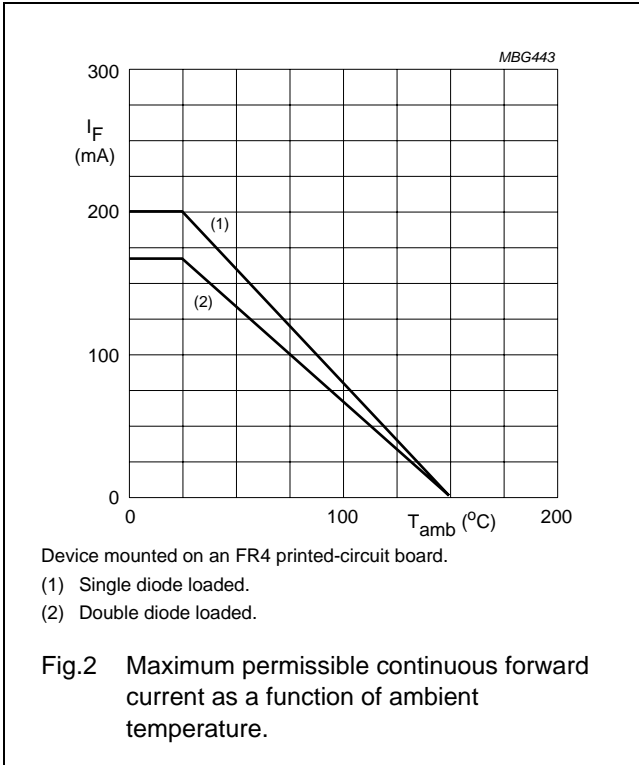
**Note**

1. Device mounted on an FR4 printed-circuit board.

High-speed double diode

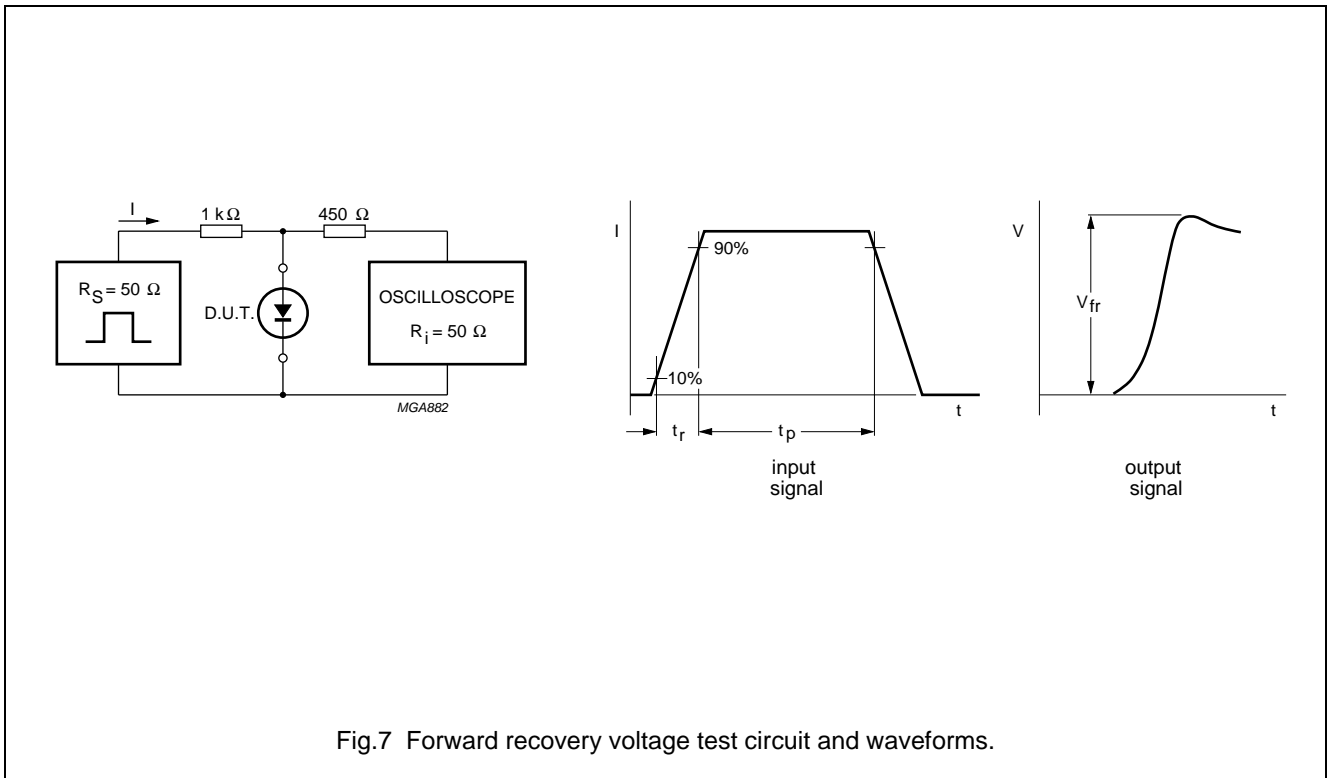
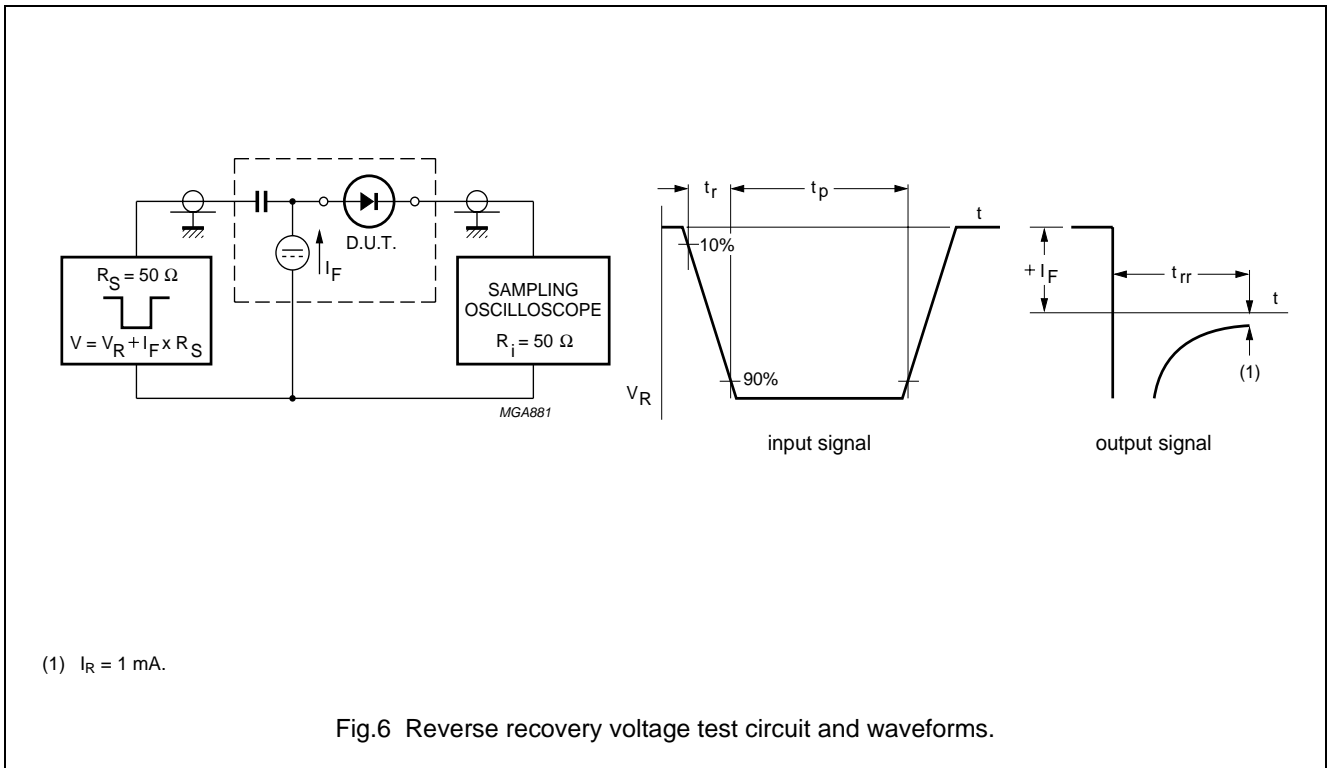
1PS300

GRAPHICAL DATA



# High-speed double diode

# 1PS300



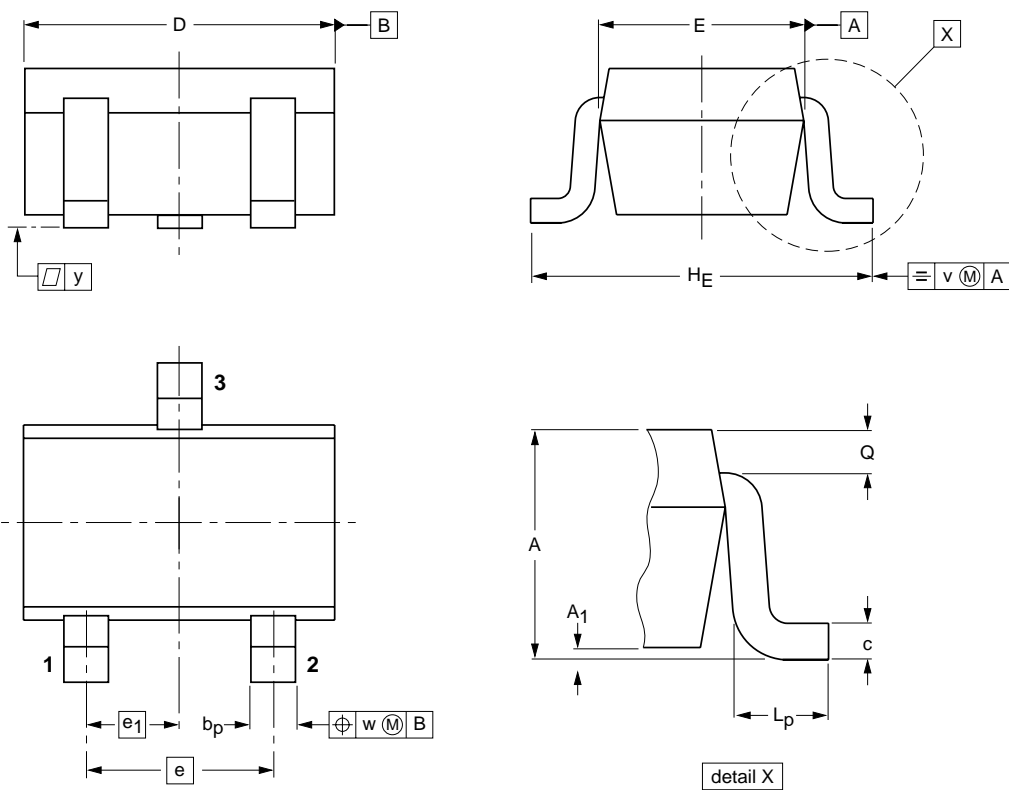
# High-speed double diode

1PS300

## PACKAGE OUTLINE

Plastic surface mounted package; 3 leads

SOT323



DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub> max	b <sub>p</sub>	c	D	E	e	e <sub>1</sub>	H <sub>E</sub>	L <sub>p</sub>	Q	v	w
mm	1.1 0.8	0.1	0.4 0.3	0.25 0.10	2.2 1.8	1.35 1.15	1.3	0.65	2.2 2.0	0.45 0.15	0.23 0.13	0.2	0.2

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT323			SC-70			97-02-28

## High-speed double diode

1PS300

## DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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